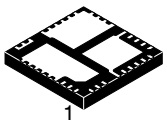
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

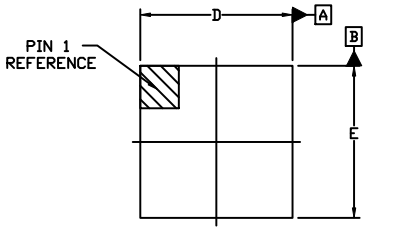
ON Semiconductor®

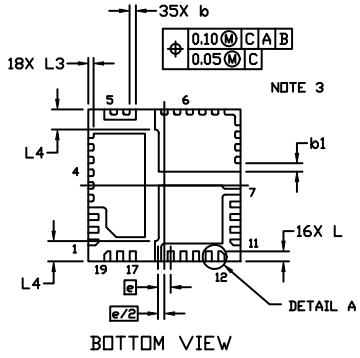


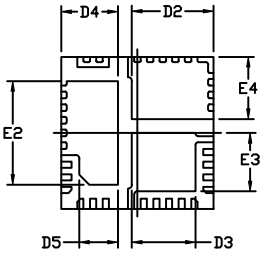
QFN19 6x6, 0.5P
CASE 485FL
ISSUE B

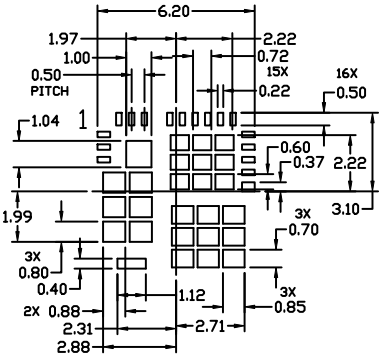
DATE 12 FEB 2019

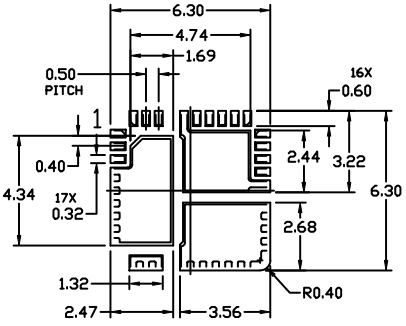
SCALE 2:1











* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	---	0.05
A3	0.20 REF		
b	0.18	0.24	0.30
b1	0.26	0.32	0.38
D	5.85	6.00	6.15
D2	3.12	3.22	3.32
D3	2.47	2.52	2.57
D4	2.13	2.23	2.33
D5	1.47	---	1.58
E	5.85	6.00	6.15
E2	4.04	---	4.14
E3	2.25	---	2.35
E4	2.35	2.45	2.55
e	0.50 BSC		
L	0.30	0.40	0.50
L3	0.10	0.20	0.30
L4	0.70	0.80	0.90

GENERIC MARKING DIAGRAM*

A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**QFN19 6x6, 0.5P**	**PAGE 1 OF 1**